

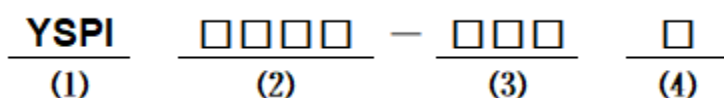
■ Features

- Molding Inductor.
- Low Profile, Low Temp.
- Large Current.
- Customize For Different Need.
- Operating temperature: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (Including self-temperature rise) .

■ Applications

- General Electronic.
- Video Device, TV, TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server, VGA Card/Module.

■ Product Identification



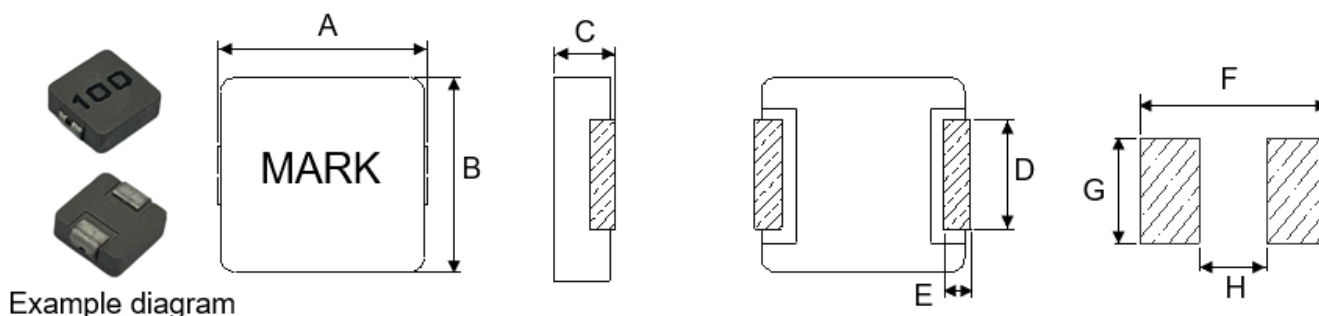
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance: N= $\pm 30\%$, M= $\pm 20\%$, K= $\pm 10\%$

■ Shapes and Dimensions (Unit: mm)



TYPE	A	B	C Max.	D	E	F Ref.	G Ref.	H Ref.
YSPI0850	8.7 ± 0.3	8.1 ± 0.2	5.0	3.0 ± 0.2	2.0 ± 0.3	9.0	3.2	4.7

■ YSPI0850 Series

Part Number	Inductance (μ H) @100KHz/1V	DCR Max. (m Ω)	Saturation Current Isat Typ.(A)	Heat Rating Current Irms Typ.(A)
YSPI0850-1R0M	1.0 $\pm$ 20%	5.5	18.0	16.0
YSPI0850-1R5M	1.5 $\pm$ 20%	6.0	16.0	13.0
YSPI0850-2R2M	2.2 $\pm$ 20%	13	15.0	10.0
YSPI0850-3R3M	3.3 $\pm$ 20%	18	13.0	8.0
YSPI0850-4R7M	4.7 $\pm$ 20%	22	11.0	7.5
YSPI0850-6R8M	6.8 $\pm$ 20%	25	10.0	7.0
YSPI0850-100M	10 $\pm$ 20%	45	8.0	6.0
YSPI0850-150M	15 $\pm$ 20%	60	5.5	5.0
YSPI0850-220M	22 $\pm$ 20%	90	5.0	4.0
YSPI0850-330M	33 $\pm$ 20%	130	4.0	3.3
YSPI0850-470M	47 $\pm$ 20%	200	3.5	2.5
YSPI0850-680M	68 $\pm$ 20%	300	3.0	2.0

※ All test data is referenced to 25 °C ambient.

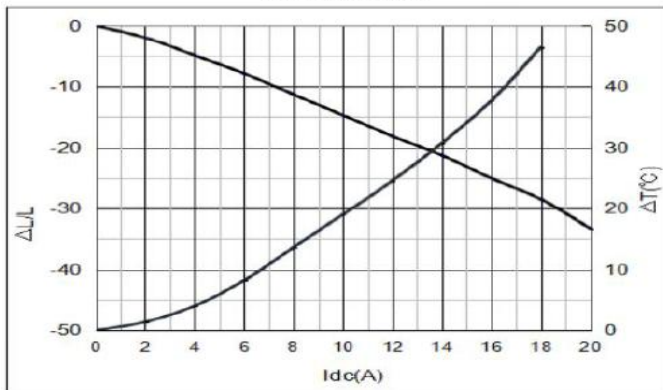
※ Irms (A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)

※ Isat(A):DC current (A) that will cause L0 to drop approximately 30%.(Internal control standards at 40% MAX)

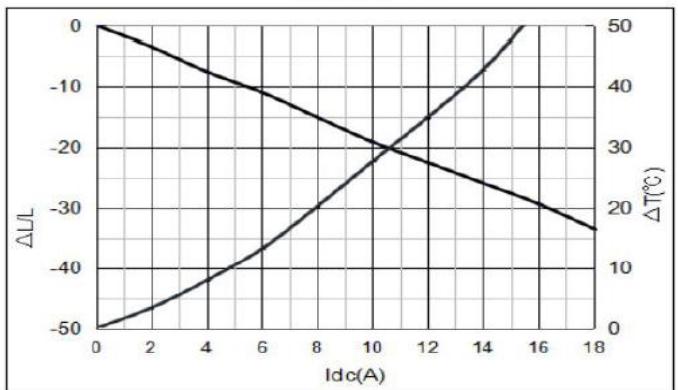
※ Absolute maximum voltage 30VDC.

■ Current Characteristic

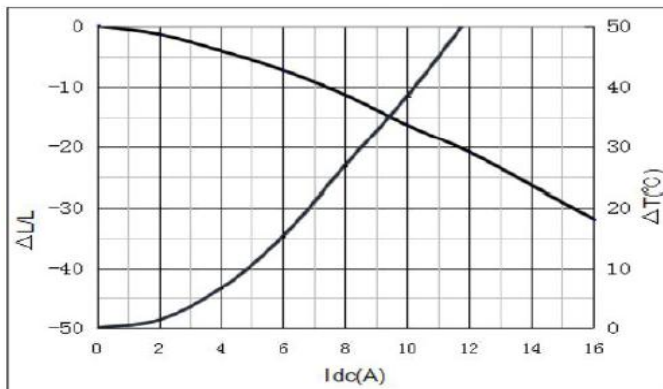
YSPI0850-1R0M



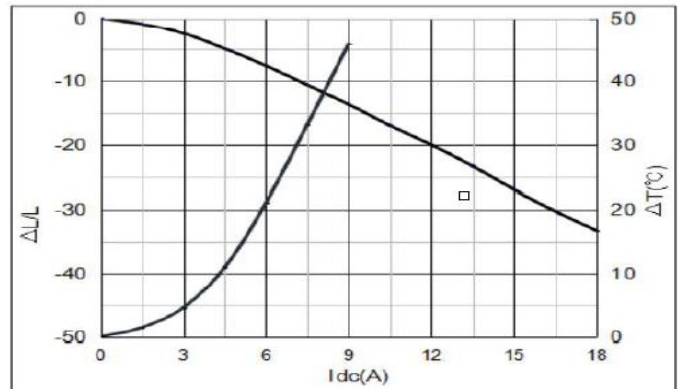
YSPI0850-1R5M



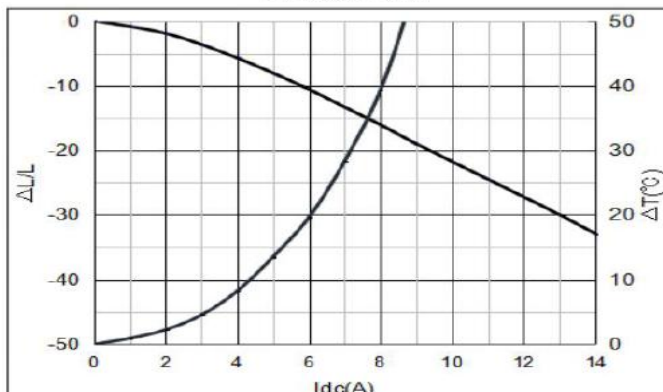
YSPI0850-2R2M



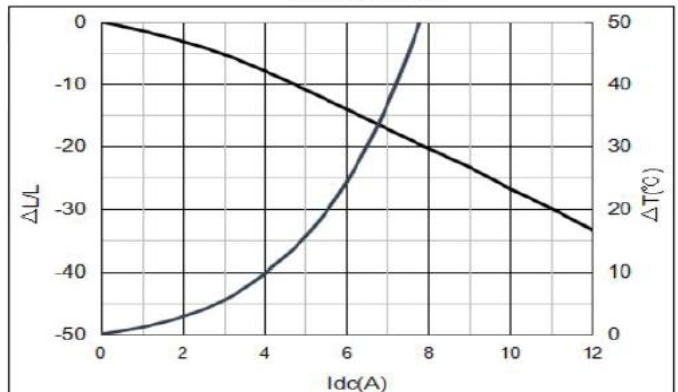
YSPI0850-3R3M



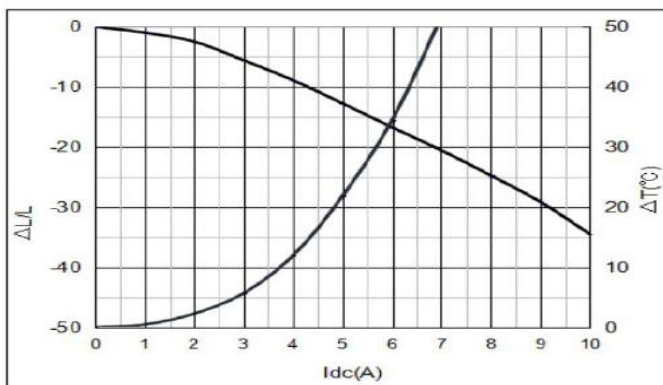
YSPI0850-4R7M



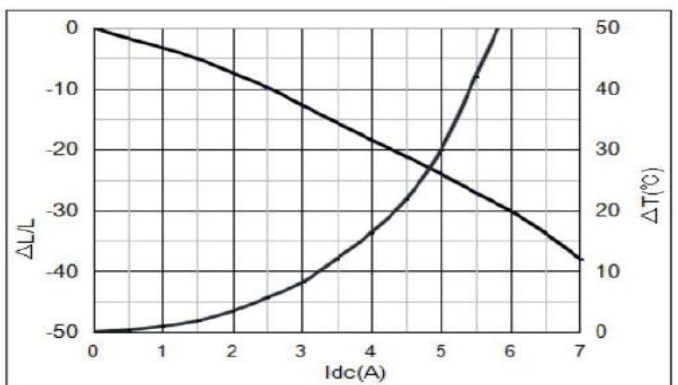
YSPI0850-6R8M



YSPI0850-100M

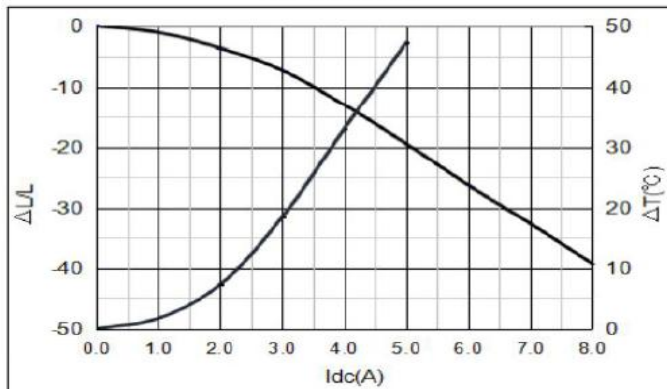


YSPI0850-150M

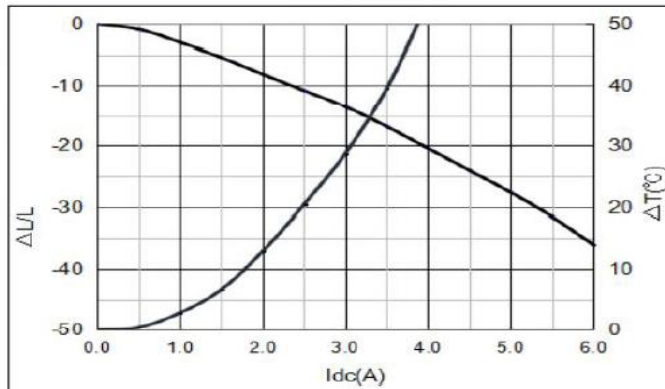


■ Current Characteristic

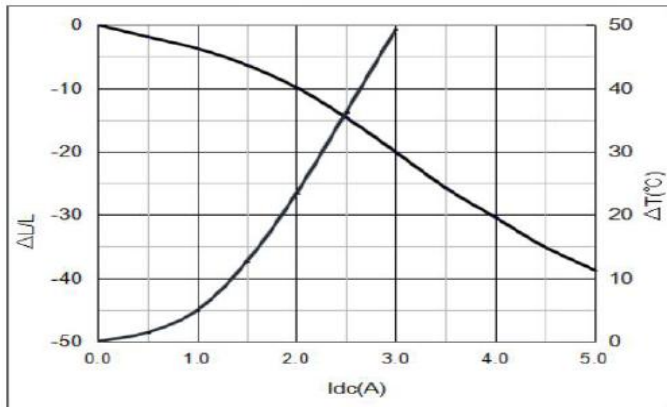
YSPI0850-220M



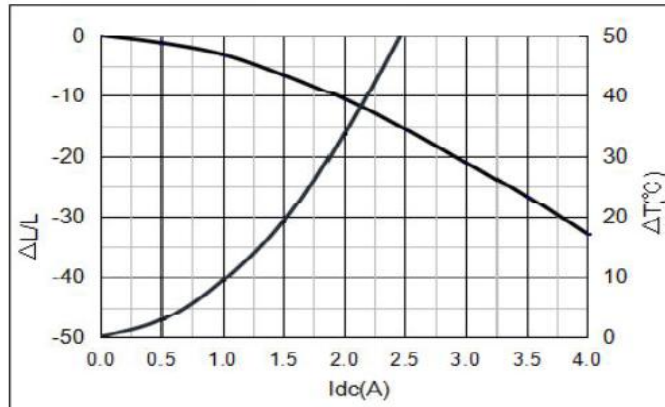
YSPI0850-330M



YSPI0850-470M



YSPI0850-680M



■ General Characteristics

NO.	ITEMS	CONDITIONS	SPECIFICATION
1	OPERATION TEMPERATURE STORAGE TEMPERATURE		-40 ~ +125 °C (INCLUDING COIL TEMPERATURE RISE) -40 ~ +125 °C
2	TEMPERATURE COEFFICIENT	-30 ~ +105 °C	0 ~ 2000ppm/°C
3	FIXING STRENGTH	SAMPLE IS PUSHED IN THREE DIRECTIONS OF X, Y AND Z WITH FORCE OF 5. 0N FOR 10±5 SECONDS. AFTER SOLDERING BETWEEN COPPER PLATE AND ELECTRODES.	NO ELECTRODE DETACHMENT.
4	RESISTANCE TO SOLDERING HEAT TEST	REFER TO THE SPEC "STD-001NP".	NO MECHANICAL BREAKAGE. DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
5	SOLDERABILITY TEST	IMMERSE THE ELECTRODE IN FLUX FOR 5 SECONDS. THEN DIP THE ELECTRODE INTO A SOLDERING BATH OF 245±5 °C FOR 2±0.5 SECONDS.	OVER 95% OF THE SURFACE BEING IMMersed SHALL BE COVERED WITH NEW SOLDER UNIFORMLY.
6	VIBRATION TEST	AMPLITUDE: 1.5mm P-P FREQUENCY:10~55~10Hz (1 MINUTE PER CYCLE) DURATION: 1 HOUR IN EACH OF X, Y, Z AXIS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
7	HUMIDITY TEST	TEMPERATURE: 40 °C ±2 °C HUMIDITY: 90%~95%RH DURATION: 96±4 HOURS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
8	THERMAL SHOCK TEST	20 CYCLES OF +105 °C FOR 30 MINUTES, -40 °C FOR 30 MINUTES. CHARACTERISTICS ARE MEASURED AFTER THE AMBIENT AIR EXPOSURE OF 1 HOUR	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
9	HIGH TEMPERATURE STORAGE TEST	TEMPERATURE: 125 °C ±2 °C DURATION: 96±4 HOURS	
10	LOW TEMPERATURE STORAGE TEST	TEMPERATURE: -40 °C ±3 °C DURATION: 96±4 HOURS.	

※ Standard testing conditions:

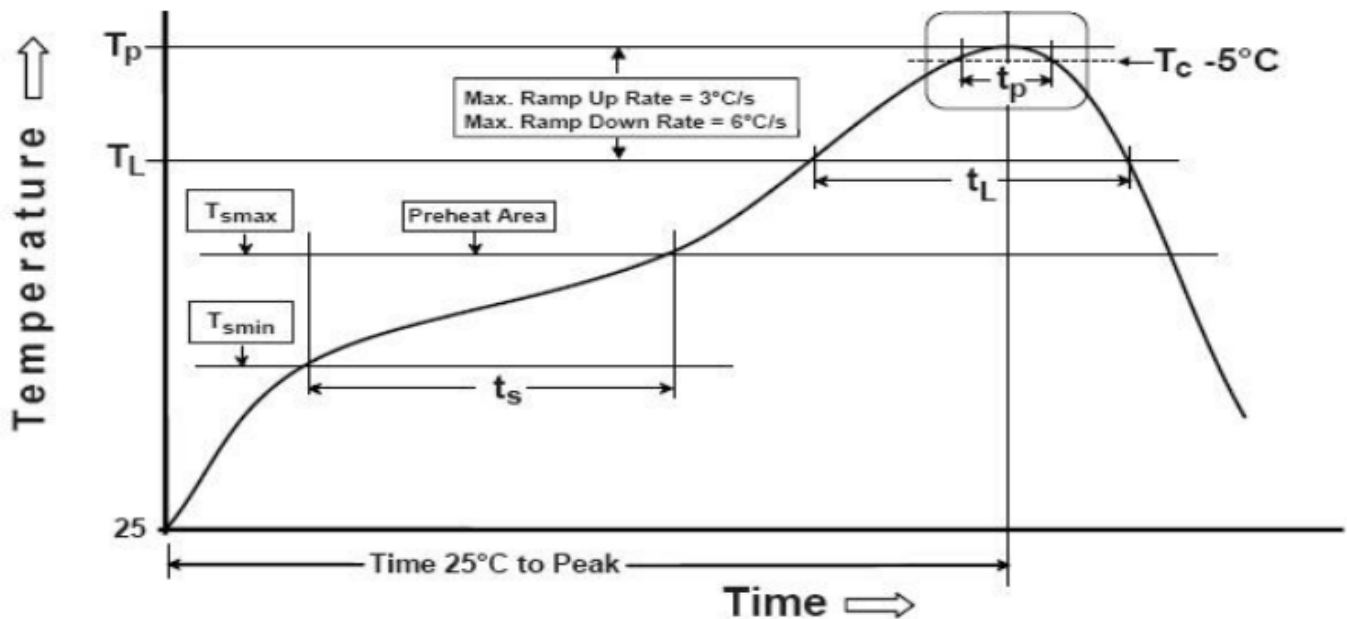
Unless otherwise specified, the standard range of atmospheric conditions for measurements and tests are as follows:

Ambient temperature: 15 °C ~ 35 °C. Relative humidity : 25% ~ 85%. Air pressure: 86kPa ~ 106kPa.

If there is doubt about the results, measurement shall be made within the following limits:

Ambient temperature: 20 °C ± 1 °C. Relative humidity: 63% ~ 67%. Air pressure: 86kPa ~ 106kPa.

Reflow profile for SMT components



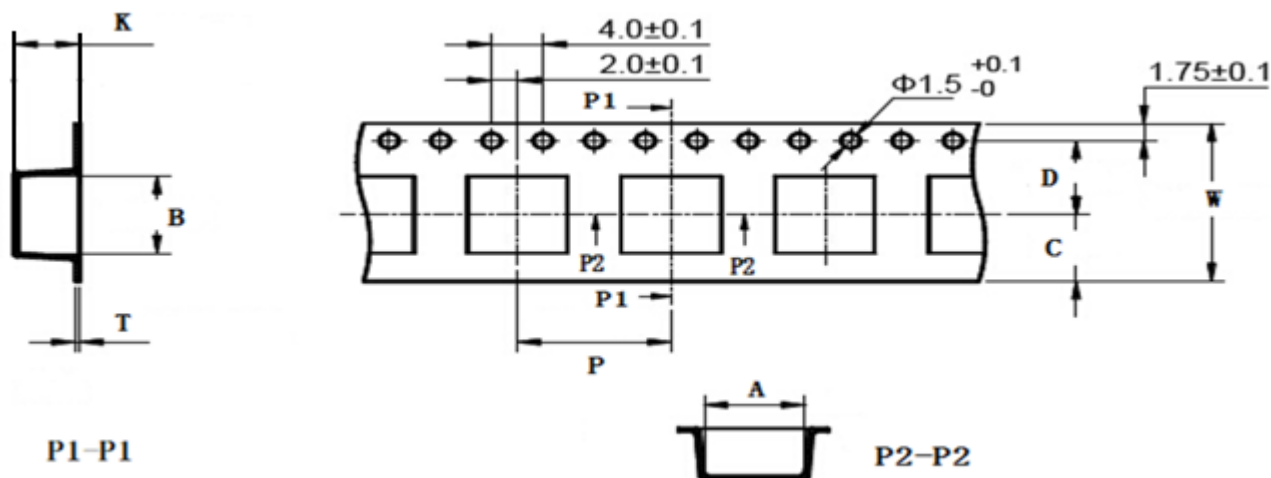
Reflow is referred to standard IPC/ JEDEC J-STD-020D

Profile Feature		Lead(Pb) Free solder
Preheat and soak	• temperature Min.(Ts min)	150°C
	• temperature Max.(Ts max)	200°C
	• time(Tsmin to Ts max)(ts)	60-120 Seconds
Average ramp up rate Tsmax to Tp		3°C/Second Max.
Liquidous temperature (T_L)		217 °C
Time (T_L) maintained above T_L		60-150 seconds
Peak package body temperature (T_p)		Table2
Time (t_p)* within 5 °C of the specified classification temperature (T_c)		30* seconds
Average Ramp-down rate (T_p to T_L)		6 °C/second max
Time 25 °C to peak temperature		8 minutes max.

Table2. Pb-Free Process - Classification Temperatures (T_c)

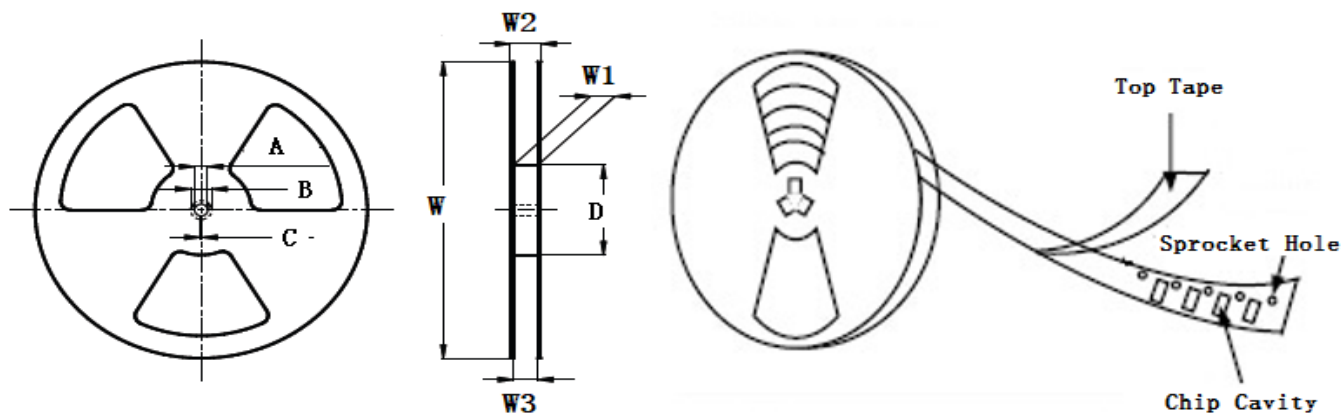
Package Thickness	Volume mm3 <350	Volume mm3 350~2000	Volume mm3 >2000
<1.6 mm	260°C	260°C	260°C
1.6mm- 2.5mm	260°C	250°C	245°C
>2.5 mm	250°C	245°C	245°C

■ Taping Dimensions(Unit:mm)



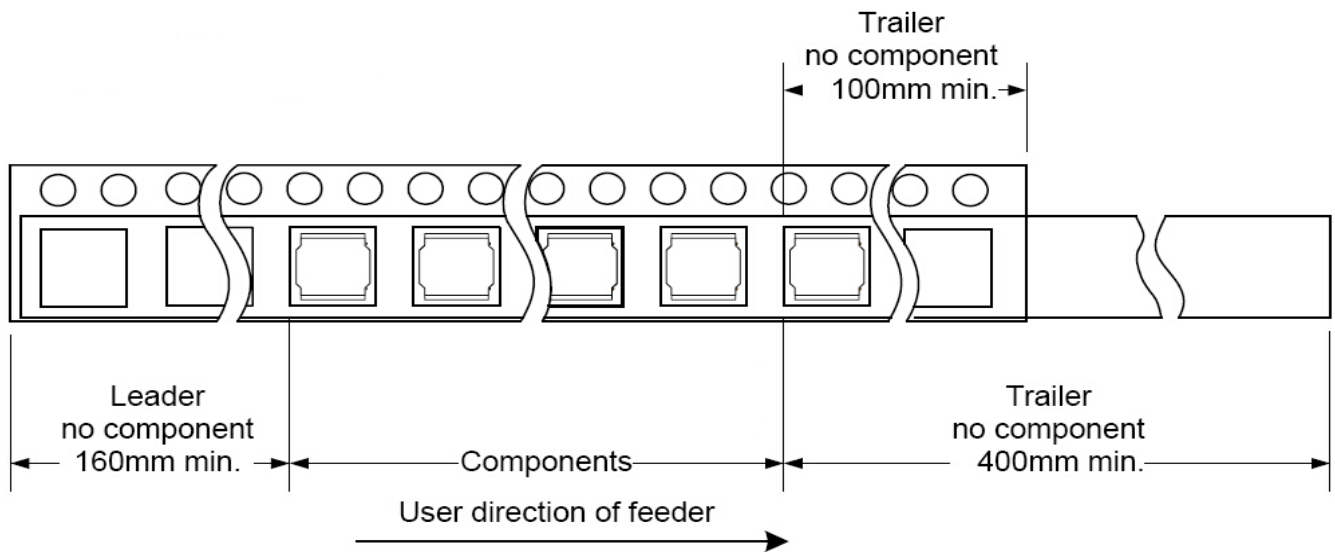
TYPE	W	A	B	C	D	P	K	T	MPQ
YSPI0850	16.0±0.2	8.35±0.1	9.1±0.1	6.75	7.5±0.1	12.0±0.1	5.2±0.1	0.40±0.10	1000

■ Reel Dimensions(Unit:mm)

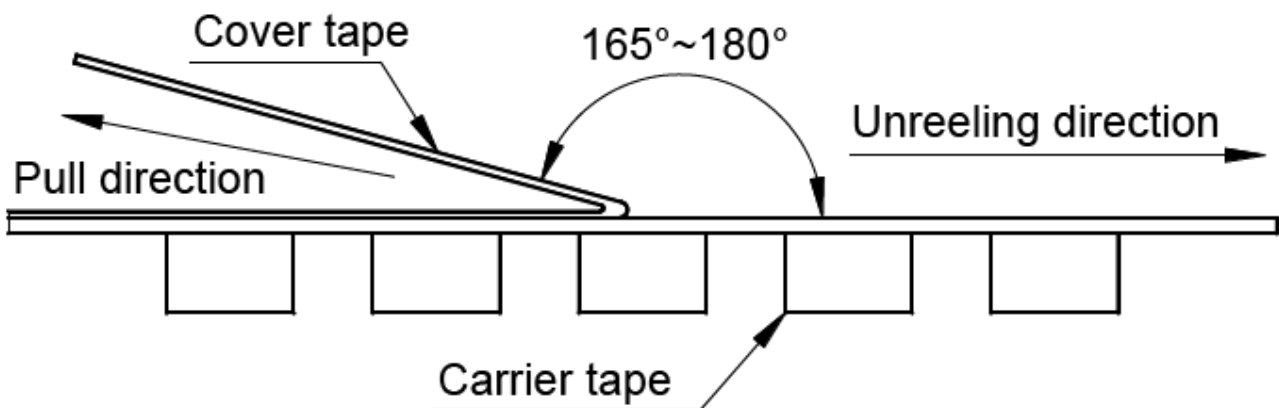


TYPE	W	W1	W2	W3	A	B	C	D
YSPI0850	330±2.0	16.4±2.00	22.4MAX	15.9 Min	13.0±0.50	21.0±0.80	2.0±0.50	100 Min

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300 ± 10 mm/min.